



2023 Semiconductor Advanced Packaging Workshop



Organized by
IEEE Electronics Packaging Society, Malaysia Section

Dates & Venues:
17th October 2023 at Bangi Resort Hotel, Selangor
or
19th October 2023 at Eastin Hotel, Penang

“ Material and Process Trends in Fan-out WLP and PLP ”

by *Dr. Tanja Braun*

Group Manager Fraunhofer IZM Berlin, Germany

Fan-out Wafer and Panel Level Packaging are gaining relevance as mass compatible advanced packaging technologies. Providing technical advantages and optimized cost for manifold applications, FOWLP and PLP are fundamentally changing the packaging infrastructure. In the past OSATs dominated high volume manufacturing, but recently new players in packaging as semiconductor foundries, PCB or LCD manufacturing companies entered this business area and are changing not only supply chains but also form factors towards larger areas. However, materials are playing an important role especially for future applications as RF, power or advanced computing applications. In addition, materials are also a key factor for cost and sustainability.

In summary the presentation will discuss recent technical developments as well as the changing ecosystem and actual advantages and challenges when moving to large panel level manufacturing.



“ Exploring Chiplets and the New Era of Advanced Packaging ”

by *E. Jan Vardaman*

President and Founder, TechSearch International, Inc.

As the industry enters the new era of heterogeneous integration, advanced packaging in the form of chiplets is becoming increasingly important. An increasing number of companies are turning to chiplets to achieve the economic advantages lost with expensive monolithic scaling, ushering in a new era of smart packaging. A chiplet is not a package, but it is a new approach to system, package, and chip design. There are many package options and careful consideration is required to select the most appropriate options for the application. Options include the emerging 3DIC format with microbumps or hybrid bonding, laminate substrate package, fan-out on substrate, and silicon interposer. Challenges include design, test, assembly, and thermal. This seminar defines chiplets and provides examples of the applications and package types in use today and what is expected for the future. Packaging challenges are highlighted and areas that require future work are documented.



“ Automotive Packaging Trends ”

The automotive sector continues to grow and the electronic content per vehicle is increasing. The move to electric vehicles (EV) is driving adoption of wide band gap materials and new packages. Power devices are increasingly important, and new form factors including embedded structure are being adopted for these applications. Many packages are leadframe-based packages. QFN remains the workhorse of the industry. Demand for Cu clip packages is increasing. What are the package choices for these application areas and how are the options changing? What infrastructure and material challenges does the industry face? This presentation discusses these growth drivers and packaging trends.

2023 Semiconductor Advanced Packaging Workshop

Mark your calendar and save the date to attend the **2023 Semiconductor Advanced Packaging Workshop** on **17th October 2023 at Bangi Resort Hotel, Selangor** or **19th October 2023 at Eastin Hotel, Penang**.

Participants will get a chance to meet and be inspired by two IEEE renowned speakers who will be sharing their expertise in the most recent packaging trends and development of emerging technologies.....

Hurry up and **sign up ONLINE today** to enjoy early bird fees!!!
*****Exclusive privilege for IEEE Members and students*****



REGISTRATION DETAILS

I. WORKSHOP VENUE SELECTION

*Note: Select only **ONE** of the respective venue*

17 th October 2023	BANGI RESORT HOTEL, SELANGOR
19 th October 2023	EASTIN HOTEL, PENANG

REGISTER ONLINE HERE

Click
<https://www.ticket2u.com.my/event/31110>



II. WORKSHOP SCHEDULE

TIME	EVENT
0800 – 0830	Registration
0830 – 1230	Session 1: Material and Process Trends in Fan-out WLP and PLP
1230 - 1330	Lunch
1330 - 1730	Session 2A: Exploring Chiplets and the New Era of Advanced Packaging Session 2B: Automotive Packaging Trends

**Organizer remains the right to change the workshop schedule without prior notice.*

Reminder:
 Please bring along a copy of printed receipt or show e-receipt during registration on the workshop day.

III. REGISTRATION FEE

CATEGORIES	EARLY BIRD (Before 1 st September 2023)	NORMAL FEE (After 1 st September 2023)
<input type="checkbox"/> IEEE MEMBER	<input type="checkbox"/> RM625	<input type="checkbox"/> RM725
<input type="checkbox"/> NON IEEE MEMBER	<input type="checkbox"/> RM775	<input type="checkbox"/> RM875
<input type="checkbox"/> STUDENTS	<input type="checkbox"/> RM450	<input type="checkbox"/> RM550

**Register in group of 5 and get the 6th attendee Free-of-charge.
 **Registration fee includes seminar, lunch, coffee breaks, certificate and a copy of the training material.*

IV. PAYMENT DETAILS

Participants are strongly encouraged to register and make the payment via the e-registration link provided above kindly contact Lau Teck Beng for necessary technical assistance.

Registration and Cancellation Policy:

1. Registration transfer is allowed for the same workshop (i.e., same date and location).
2. Registrants who cancel their registration for any reason will receive a partial refund according to the following schedule:
 Registrations cancelled more than 30 days before the event will be refunded 80% of the registration fees, no refund less than 30days.

Join IEEE-EPS Malaysia Chapter

- Become a member of IEEE-EPS Malaysia Section and enjoy big discounts on our future seminars. Here is how to become a member.
1. Membership application info is at: <https://www.ieee.org/membership-catalog/productdetail/showProductDetailPage.html?product=MEMEP021>
 2. Membership benefit: http://www.ieee.org/membership_services/membership/benefits/index.html
 3. EPS home page: <https://ieeee-epsmalaysia.org/>

Organizer contact:

Organizer: IEEE EPS MALAYSIA
 Email: teckbeng.lau@gmail.com

*Who should attend: Engineers and managers responsible for advanced packaging development, package design and package quality & reliability are welcomed to join
 2023 Semiconductor Advanced Packaging Workshop.....*